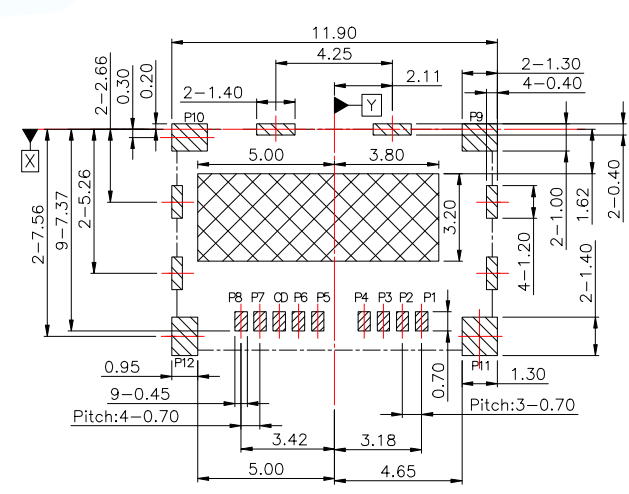
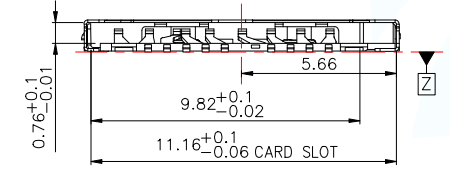
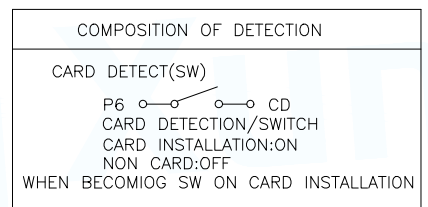
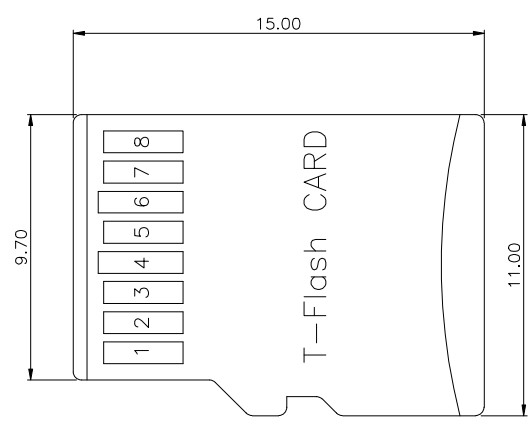


- NOTE:
- Material:
 - 1-1 Housing:High Temperature Thermoplastic, (LCP MG350)Color Black UL 94V-0.
 - 1-2 Contact: Phosphor Bronze(C5210R-SH T=0.12mm)
 - 1-3 Cover: SUS304-H T=0.10mm
 - Plating:
 - 2-1 Contact terminal: Contact area: Gold 2u" Min.Middle Pd-Ni 8u" min. Solder area: Gold 1u" Min. Underplating: Ni overall 80U" Min.
 - 2-2 Cover: Underplating: Ni overall 30U" Min. Solder area: Gold 1u" Min.
 - Specification:
 - 3-1.Contact Current Rating:0.5Amperes.
 - 3-2.Dielectric Withstanding Voltage:AC500V r.m.s.
 - 3-3.Insulation Resistance:1000 Megohms Minimum At DC 500V.
 - 3-4.Contact Resistance:100 mΩ Maximum.
 - 3-5.Mating Cycles:5,000 Cycles.
 - 3-6.Operating Temperature:-25°C~+60°C.
 - Product Compliant to RoHS Directive 2002/95/EC and ELV 2000/53/EC
 - Part Must Comply Taisol HF WD-3-I-091 Specification.
 - Recommending A Metal More Than 0.15mm Thick. Please Confirm Solderability, If Use A Metal Mask Less Than 0.15mm Thick.



RECOMMEND P.C.B LAYOUT
(General tolerance ±0.05)

- PAD AREA
- KEEP OUT AREA
- NO COPPER AREA
- GND PATTERN ONLY



PIN NO.	NAME	YYPE	DESCRIPTION
1	DAT2	I/O/PP	DATE LINE(BIT2)
2	CD/DAT3	I/O/PP	CARD DETECT DATE LIN(BIT3)
3	CMD	PP	COMMAND RESPONSE
4	VDD	S	SUPPLY VOLTAGE
5	CLK	I	CLOCK
6	VSS	S	SUPPLY VOLTAGE GROUND
7	DAT0	I/O/PP	DATE LINE(BIT0)
8	DAT1	I/O/PP	DATE LINE(BIT1)
9-12	GND		

MANUFACTURE DWG			东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE: Micro SD H1.15 CARD CONN	
DECIMALS:	ANGLES:	CUSTOMER COPY	PAR	TF-128-ARP9
.X:±0.35	X.':±2'		DWN	
.XX:±0.20	X.X':±1'		CHKD	
.XXX:±0.10		APVD		
		SCALE1:1	UNIT:MM	
		SIZE:A4	SHEET:1F1	REV:A